

BAV16WS-Q1

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BAV16WS-Q1

200mW Surface Mount Switching Diode:100V

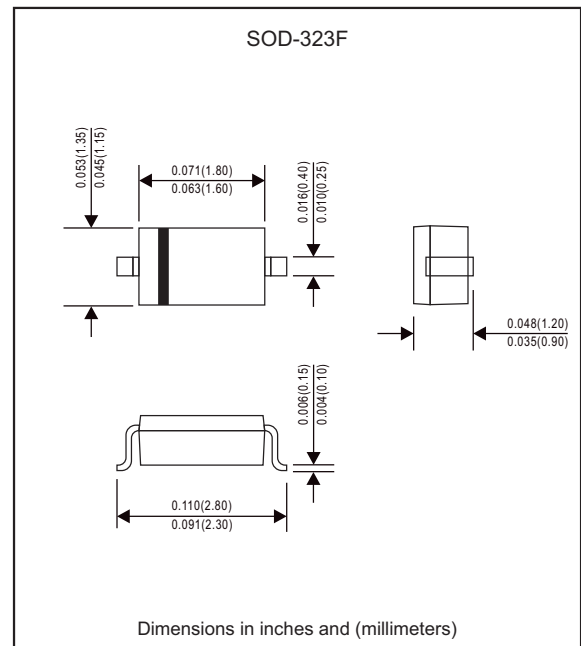
Features

- Fast switching speed.
- Electrically identical to standard JEDEC.
- Surface mount package ideally suited for automatic insertion.
- Tiny plastic SMD package.
- High Conductance.
- Silicon epitaxial planar chip.
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- Qualified to AEC-Q101 standards for high reliability.
- Suffix "-H" indicates Halogen-free part, ex. BAV16WS-Q1-H.

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323F
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.005 gram

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	Symbol	BAV16WS-Q1	UNIT
Reverse voltage	V_R	75	V
Peak reverse voltage	V_{RM}	100	V
RMS voltage	V_{RMS}	50	V
Maximum DC blocking voltage	V_{DC}	75	V
Maximum average forward current at $T_A = 25^\circ\text{C}$	I_{AV}	150	mA
Peak forward surge current, 1.0us	I_{FSM}	2.0	A
Power Dissipation derate above 25°C	P_D	200	mW
Maximum forward voltage	V_F	0.715@0.001A 0.855@0.01A 1.0@0.05A 1.25@0.15A	V
Maximum DC reverse current at rated DC blocking voltage $T_J = 25^\circ\text{C}$	I_R	0.025@20V 1.0@75V	uA
Maximum Junction capacitance (Notes 1)	C_J	2.0	pF
Maximum reverse recovery (Notes 2)	t_{rr}	4.0	ns
Maximum thermal resistance	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Notes :

1. C_J at $V_R = 0V$, $f = 1\text{MHz}$

2. From $I_F = 10\text{mA}$ to $I_R = 1\text{mA}$, $V_R = 6V$, $R_L = 100\Omega$

Rating and characteristic curves (BAV16WS-Q1)

Fig. 1 TYPICAL FORWARD CHARACTERISTICS

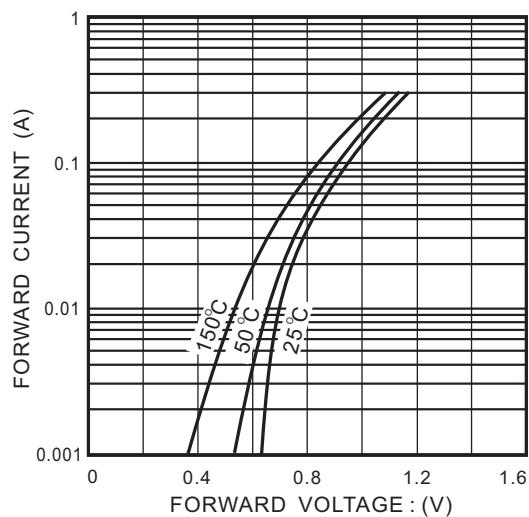


Fig. 2 TYPICAL REVERSE CHARACTERISTICS

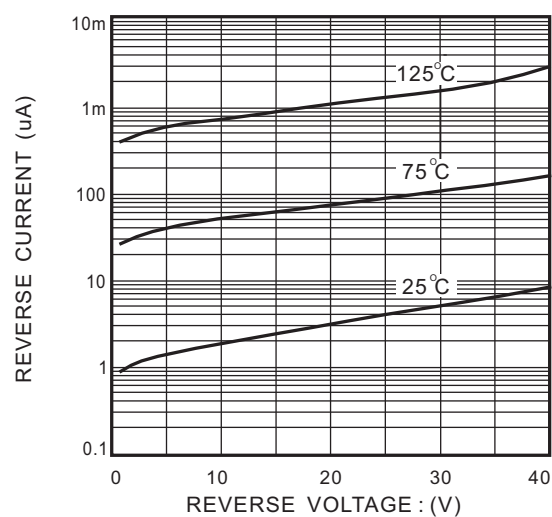


FIG.3-TYPICAL JUNCTION CAPACITANCE

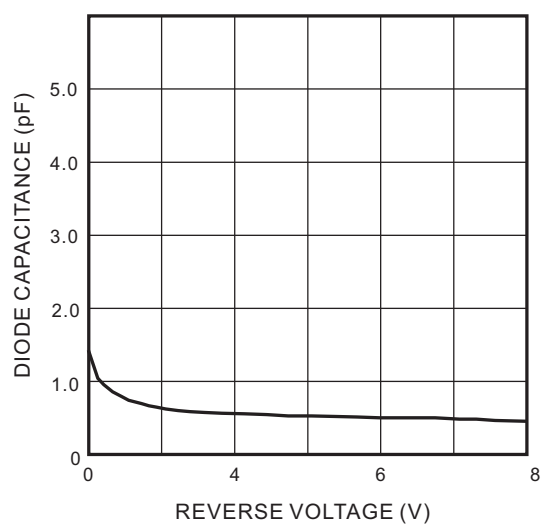
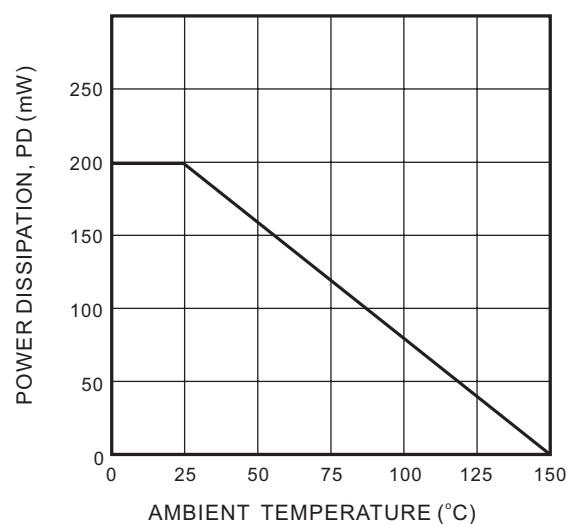


Fig. 4 POWER DERATING CURVE

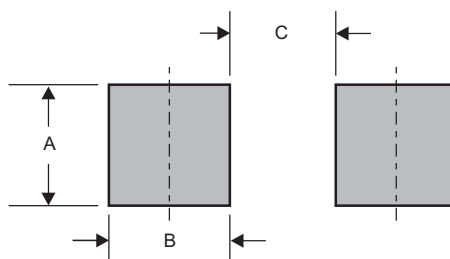


BAV16WS-Q1**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
BAV16WS-Q1	W2

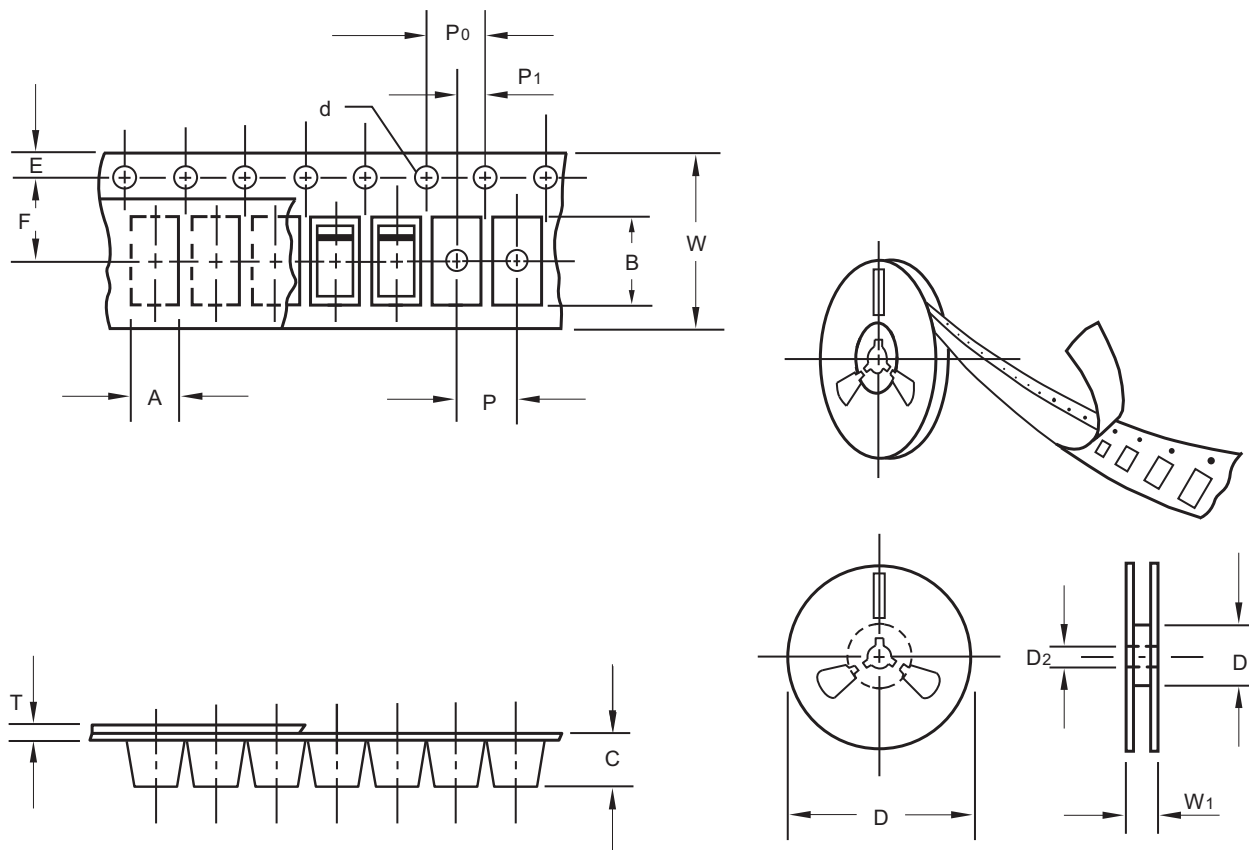
Suggested solder pad layout

Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323F	0.033 (0.83)	0.025 (0.63)	0.063 (1.60)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323F
Carrier width	A	0.1	1.46
Carrier length	B	0.1	2.95
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

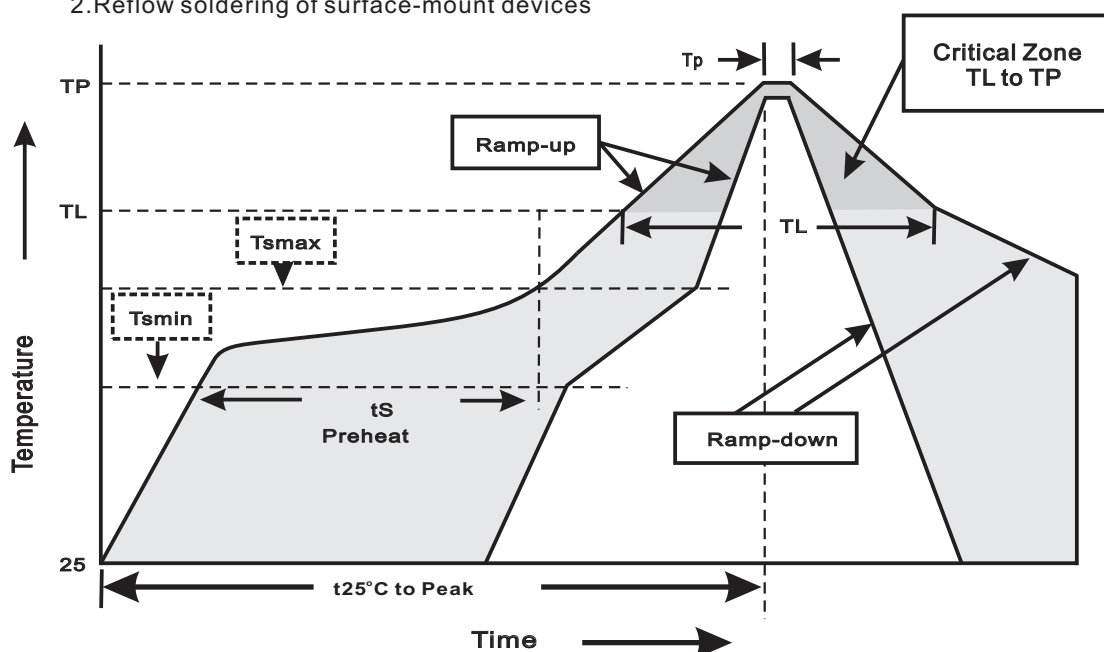
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323F	7"	3,000	4.0	30,000	183*183*123	178	382*262*387	240,000	8.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _p)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

BAV16WS-Q1**High reliability test capabilities**

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C , Rated Current (Io=Iomax.) Test Duration:1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	80% Rated VR (Tj=Tjmax.) Test Duration:1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=125°C Test Duration: 1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C (15min) to 150°C (15min) Test Cycles: 1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration:96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C, On/Io Max. 2min, Off/2min, Test Cycles:15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245±5°C for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85% Relative humidity Test Duration:1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260±5°C for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration:1000hrs	JESD22-A101